Lighting ColorYellow Green

• Red

LNJ115W8PRA

Surface Mounting Chip LED

TSS-2 Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

• Yellow Green							
Parameter	Symbol	Rating	Unit				
Power dissipation	P _D	60	mW				
Forward current	I _F	20	mA				
Pulse forward current *	I _{FP}	60	mA				
Reverse voltage	V _R	4	V				
Operating ambient temperature	T _{opr}	-30 to +85	°C				
Storage temperature	T _{stg}	-40 to +100	°C				

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Red

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	50	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

• Yellow Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	1.8	5.0	17.7	mcd
Reverse current	I _R	$V_R = 4 V_{Q}$			10	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

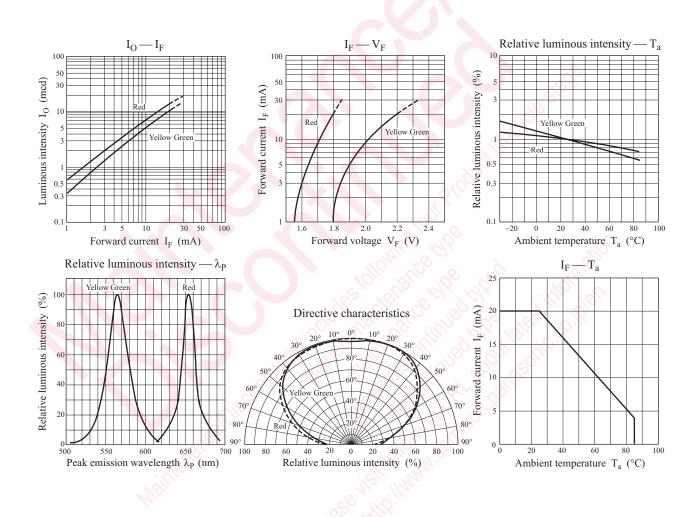
LNJ115W8PRA

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\blacksquare Electro-Optical Characteristics (Continued) $T_a\,{=}\,25^\circ C$

• Red

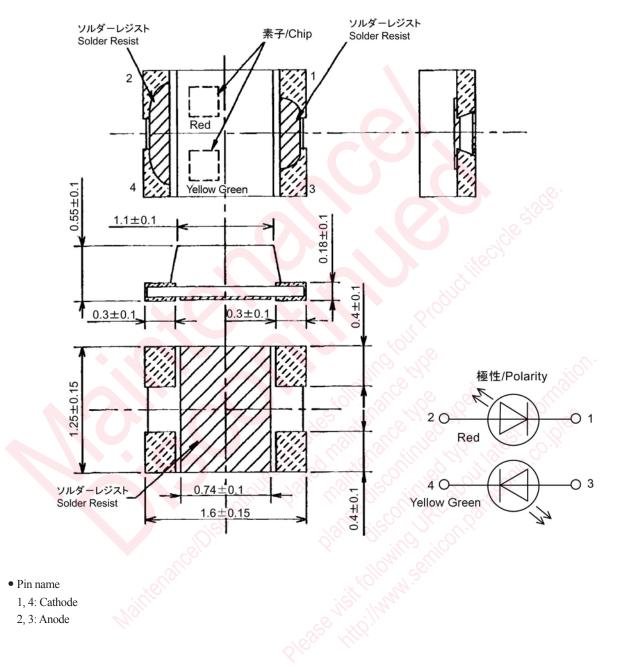
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 10 \text{ mA}$	2.2	6.7	18.8	mcd
Reverse current	I _R	$V_R = 3 V$			100	μΑ
Forward voltage	V _F	$I_{\rm F} = 10 {\rm mA}$		1.72	2.5	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 {\rm mA}$		655		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 {\rm mA}$		20		nm



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Package (Unit: mm)

KLTFTN4K1540



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